FAREWELL TO THE MERELY WIRED CIRCUITBOARDS

HIRAI PRECISION LTCC

The foundry service of HIRAI LTCC substrates targets high Q, dimensional precision and higher yield for RF, μ- and mm-wave applications TOWARD 1 MODULE & 1 CHIP RF.

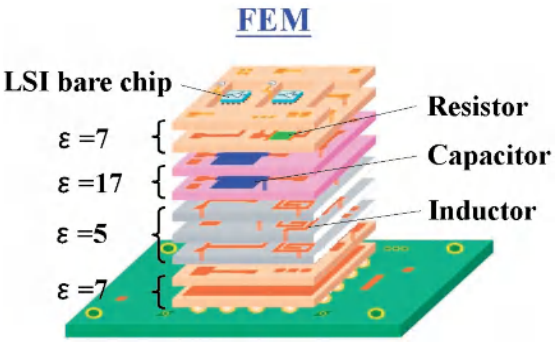
FEATURES

High Q	Thin Film and Printed Metals with Minimal RF Resistivity
Fine Pitch	L/S=30μm/30μm or less
Thin Layer	Thickness of 25μm or less
Big Panel	Up to 180 mm sq.
Embedded	L, C, R with Different Permittivities (5.0, 7.1, 18.3, ...)

APPLICATIONS

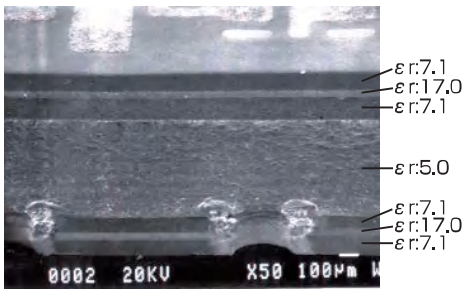
RF, μ- and mm-wave FEM, SiP, Antenna

①LTCC Substrate with Thin Film Metallization
②RF Component Sintered by Microwave Oven
③WLAN FEM with Embedded Diplexer

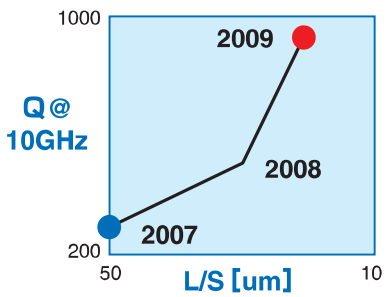


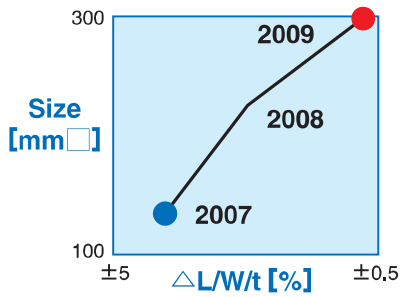
SERVICES

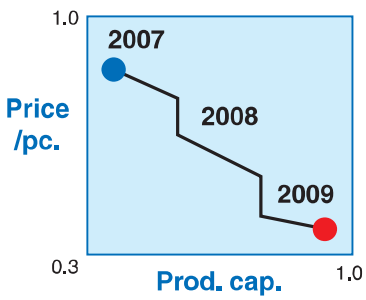
Short T.A.T.		ONE WEEK, from design freeze to the shipment
Design	**Library**	Passive Elements, Up to 67GHz
	Support	RF, μ- and mm-wave Circuit Design to be Embedded
Inspection Test		DC and RF, Up to 67 GHz
Security		Data Transfer by Cyphering
Partnership		Special Arrangements for the Iterative Dev. Contract



ROADMAP







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